



## Material Content Data Sheet



<b>Sales Product Name</b>		SGD02N60		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA000269720						
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		363.69 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.871	0.24	0.24	2395	2395
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		592	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		178	
	non noble metal	copper	7440-50-8	215.017	59.11	59.19	591206	591976
wire	non noble metal	aluminium	7429-90-5	0.509	0.14	0.14	1400	1400
encapsulation	organic material	carbon black	1333-86-4	1.230	0.34		3382	
	inorganic material	antimonytrioxide	1309-64-4	2.460	0.68		6765	
	plastics	brominated resin	-	2.460	0.68		6765	
	plastics	epoxy resin	-	24.603	6.76		67649	
	inorganic material	silicondioxide	60676-86-0	92.263	25.37	33.83	253684	338245
leadfinish	non noble metal	tin	7440-31-5	3.740	1.03	1.03	10284	10284
plating	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	250	251
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
solder	noble metal	silver	7440-22-4	0.024	0.01		66	
	non noble metal	tin	7440-31-5	0.019	0.01		53	
	non noble metal	lead	7439-92-1	0.920	0.25	0.27	2531	2650
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		53	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	copper	7440-50-8	19.177	5.27	5.28	52730	52799
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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